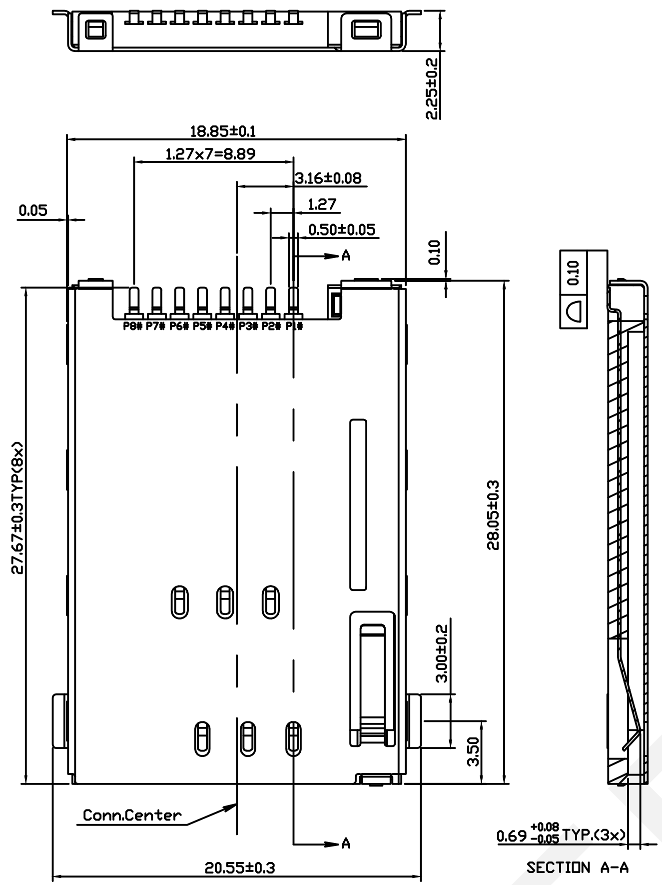
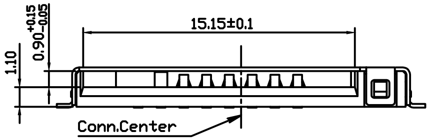
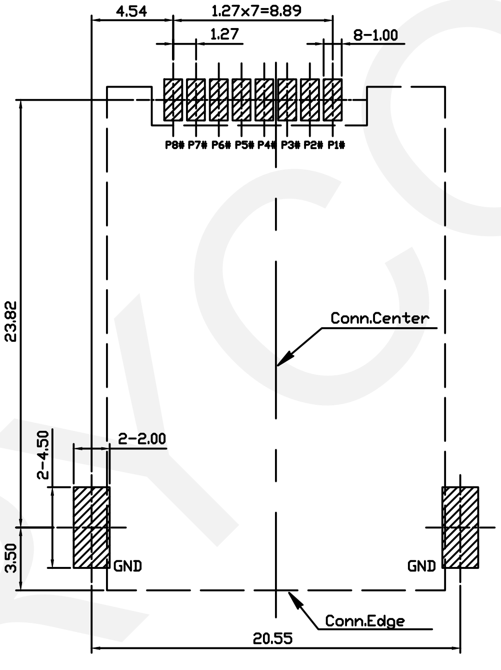




PIN NO.	Description
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	CD SW LOWER
P8#	CD SW UPPER



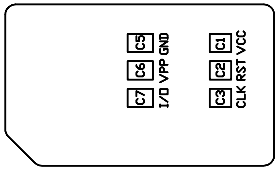
RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES(±0.05)

▨ SOLDER AREA

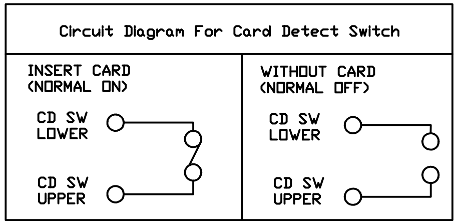
Material:
Housing:Hi-Temp Plastic,UL94V-0.Rated
Contact:Copper Alloy
Shell:Stainless Steel.SUS 301, T=0.20mm

Plating:
Contact Area:G/F Plated Over 30u" Nickel
Solder Area:80u" Tin Plated Over 30u" Nickel
Under Plate:30u" Min Nickel.
Shell:30u" Min,Nickel Plated Over All,Solder
Area:Gold Flash

Electrical:
Current Rating:0.5 A
Dielectric Withstanding Voltage:250V AC/DC
Insulation Resistance:500MΩ Min.
Contact Resistance:100mΩ Max
Mating Cycles:5000 Insertions.
Operating Temperature:-40°C TO+85°C



SIM Diagram
Chip Face Down



NINGBO ERYCO ELECTRONIC CO.,LTD

UNITS:mm	SHEET SIZE: A4		SCALE:---
0~3	3~18	18~50	50~120
±0.12	±0.15	±0.3	±0.5

DRWN BY PAN
CHK'D BY FENG
APPR BY ZHAN

Micro SIM CONN:PUSH/PUSH,
6Pin,H2.2mm,SMD With CD Pin

THIRD ANGLE PROJECTION

ERYAYIM-030A-6P-H2.2-R